

T-1 (3mm) SOLID STATE LAMP

Part Number: L-7104SEC-J3

Hyper Red

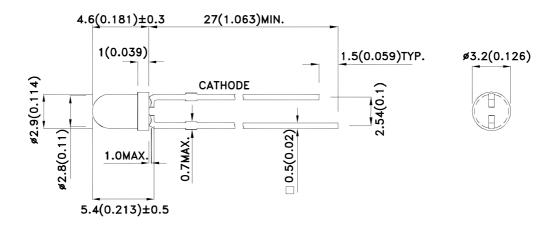
Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.

 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

DATE: JUL/27/2010 **REV NO: V.4** SPEC NO: DSAI9730 PAGE: 1 OF 6 APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.F.Lv ERP: 1101029050

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		, , , , , , , , , , , , , , , , , , ,	Min.	Тур.	201/2
L-7104SEC-J3	Hyper Red (AlGaInP)	WATER CLEAR	4000	7000	34°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	25		nm	IF=20mA
С	Capacitance	Hyper Red	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	2.2	2.8	V	IF=20mA
IR	Reverse Current	Hyper Red		10	uA	VR = 5V

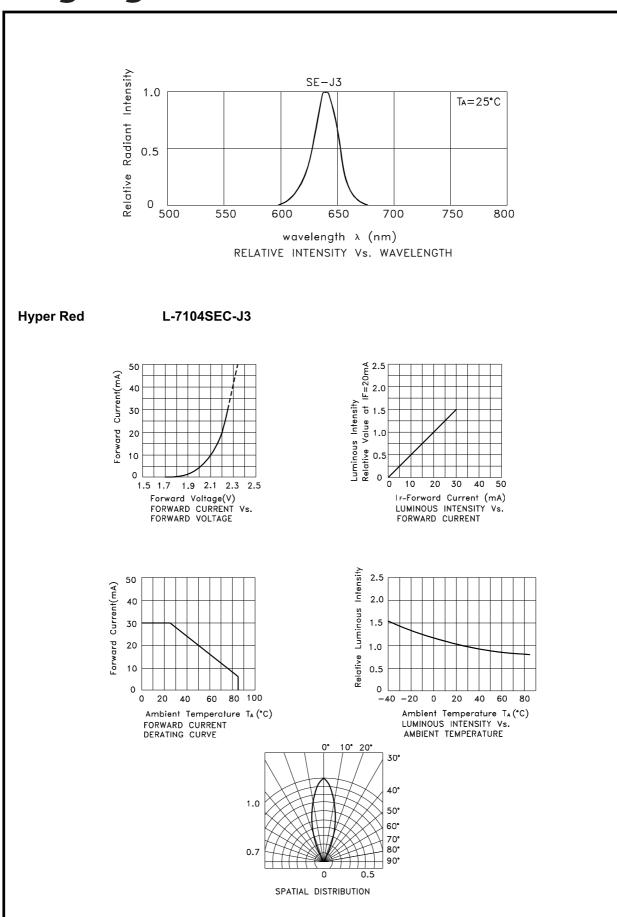
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

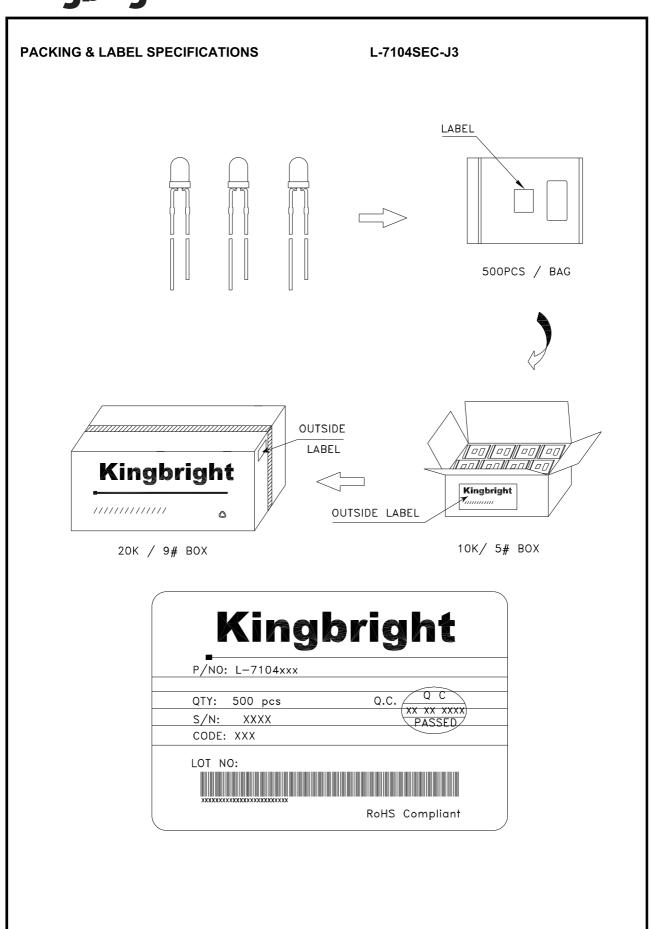
Parameter	Hyper Red	Units		
Power dissipation	84	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
 5mm below package base.

SPEC NO: DSAI9730 **REV NO: V.4** DATE: JUL/27/2010 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.F.Lv ERP: 1101029050



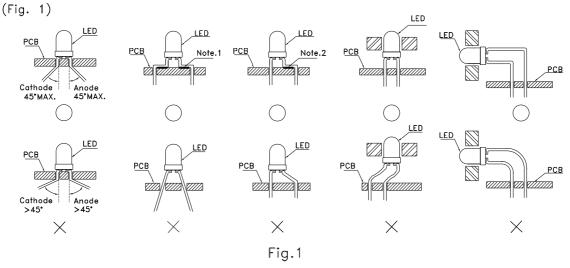
SPEC NO: DSAI9730 REV NO: V.4 DATE: JUL/27/2010 PAGE: 3 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.F.Lv ERP: 1101029050



SPEC NO: DSAI9730 APPROVED: WYNEC REV NO: V.4 CHECKED: Allen Liu DATE: JUL/27/2010 DRAWN: Y.F.Lv PAGE: 4 OF 6 ERP: 1101029050

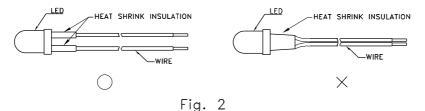
LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

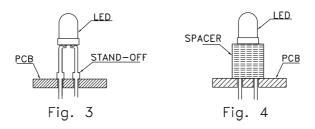


" \bigcirc " Correct mounting method " \times " Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)



3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

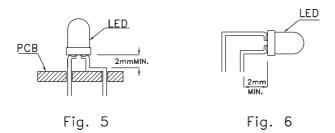


SPEC NO: DSAI9730 REV NO: V.4 D.
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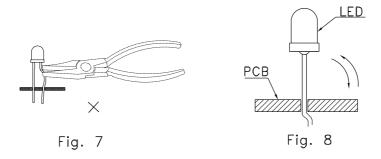
DATE: JUL/27/2010 PAGE: 5 OF 6
DRAWN: Y.F.Lv ERP: 1101029050

LEAD FORMING PROCEDURES

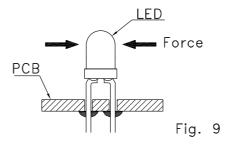
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



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SPEC NO: DSAI9730 **REV NO: V.4** DATE: JUL/27/2010 PAGE: 6 OF 6 APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.F.Lv